GigaDevice Semiconductor Inc.

Arm® Cortex®-M33 32-bit MCU

Application Note
AN010
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1. Introduction

In the field of low power control and application, the power consumption of MCU in low power mode is always paid much attention. GD32E5 series provide low power mode Deep-sleep 2, whose power consumption is much lower than that of Deep-sleep mode. In Deep-sleep 2 mode, all clocks in the 1.1V domain are off, and all of IRC8M, IRC48M, HXTAL and PLLs are disabled. The power of COREOFF0/COREOFF1 domain is cut off. The contents of SRAM except for the first 32KB and registers in COREOFF0/COREOFF1 domain are lost. In Deep-sleep 2 mode, part of the circuit including CPU will be power down, so when wake up from the Deep-sleep 2 mode, the MCU will generate a system reset. The register configurations of peripherals except FMC, PMU, RCU, EXTI, GPIO, FWDGT, WWDGT, USART5 and I2C3 are lost. In order to keep the scene before entering the Deep-sleep 2 mode and recover the scene after waking up from Deep-sleep 2 mode, and meanwhile achieve low power consumption, a hardware and software cooperation mechanism is designed as follows.
2. **SRAM partition**

After waking up from the Deep-sleep 2 mode, the contents of the first 32KB of SRAM will not be lost. So the first 32KB of SRAM is retained for real-time data that needs to be recovered. Configure the IRAM in keil in Figure 2-1. Configuration of IRAM in keil. The SRAM used by the keil start from the 0x20002000. And the "No Init" should be checked so that the zero space does not need to be initialized. The global variables must defined outside the main function without initialization, and initialized in the main function. If the global variables are initialized when defined outside the main function, when waked up from Deep-sleep 2 mode, the value of the global variables may be changed when initializing the stack before the main function.

**Figure 2-1. Configuration of IRAM in keil**

As is shown in Figure 2-2. SRAM partition, two stacks are allocated, STACK 1 is allocated by compiler automatically, STACK 2 is allocated by user. Suppose that the global variables take up amount of SRAM space, and there is not enough space for the STACK 1 in the first 32KB of SRAM, the data in the STACK 1 will be lost when the MCU enters Deep-sleep 2 mode. The STACK 2 and the global variables locates in the first 32KB of SRAM, when waked up from the Deep-sleep 2 mode, the data in the STACK 2 and the global variables will not be lost. When waked up from the Deep-sleep 2 mode, the values of RCU registers are retained, but PLL will be reset, so it is recommended to configure the clock before main function.

**Figure 2-2. SRAM partition**
Wakeup from Deep-sleep 2 and recover the scene

RAM

STACK 2
- 0x20000000
- 0x20001F00
- 0x20002000

global variables

STACK 1
- 0x20008000 (32KB)
- 0x20001F00
3. **Preserve and recover the scene**

In Deep-sleep 2 mode, some circuitry (including CPU) will power down, so it needs to be reset after waking up. A mechanism is designed for software and hardware to work together to recover the scene, so that the program could continue to run where it had entered low power mode. The main program flow is shown in *Figure 3-1. The main program flowchart*. The red line is only for the wakeup flow.

*Figure 3-1. The main program flowchart*
3.1. Apply for the second STACK

At the beginning of the main function, STACK 2 is applied for the application. The stack pointer points to address 0x20001F00, then the application will use STACK 2. The STACK 2 can be modified by user according to the actual stack size need by the application.

Table 3-1. Apply for STACK 2

<table>
<thead>
<tr>
<th>Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>__set_MSP(0x20001F00);</td>
</tr>
</tbody>
</table>

3.2. Preserve the sence

Before entering the Deep-sleep 2 mode, the values of registers that should not be reset can be stored in the global variables in the first 32KB of SRAM. As is shown in Table 3-2. Preserve the sence.

Table 3-2. Preserve the sence

/* store the register configuration of EXMC */
exmc_config[0] = EXMC_SNCTL0;
exmc_config[1] = EXMC_SNTCFG0;
exmc_config[2] = EXMC_SNWTCFG0;

/* store the register configuration of USART */
usart_config[0] = USART_BAUD(EVAL_COM0);
usart_config[1] = USART_CTL0(EVAL_COM0);

Then store the SP and LR at address 0x20000000 and 0x20000004 respectively before entering the Deep-sleep 2 mode.

Table 3-3. Store the SP and LR

```c
void pmu_deepsleep2_status_store(void)
{
    __asm__ __volatile__(
        "push {r0-r12}\n"
        "ldr r0,=0x20000000\n"
        "str sp,[r0]\n"
        "ldr r0,=0x20000004\n"
        "str lr,[r0]\n"
        "wfi\n"
    );
}
```
Wakeup from Deep-sleep 2 and recover the scene

void pmu_to_deepsleepmode_2(uint32_t ldo, uint8_t deepsleepmode2cmd)
{
    /* clear STBMOD and LDOLP bits */
    PMU_CTL0 &= ~(uint32_t)(PMU_CTL0_STBMOD | PMU_CTL0_LDOLP);
    /* clear deep-sleep 1 mode enable bit */
    PMU_CTL1 &= ~PMU_CTL1_DPMOD1;
    /* enable deep-sleep 2 mode */
    PMU_CTL1 |= PMU_CTL1_DPMOD2;
    /* configure LDOLP bit */
    PMU_CTL0 |= ldo;
    /* set sleepdeep bit of Cortex-M33 system control register */
    SCB_SCR |= SCB_SCR_SLEEPDEEP_Msk;
    /* select WFI or WFE command to enter deepsleep mode 2 */
    if(WFI_CMD == deepsleepmode2cmd){
        pmu_deepsleep2_status_store();
    }else{
        __SEV();
        __WFE();
        __WFE();
    }
    /* reset sleepdeep bit of Cortex-M33 system control register */
    SCB_SCR &= ~(uint32_t)SCB_SCR_SLEEPDEEP_Msk;
    PMU_CTL1 &= ~PMU_CTL1_DPMOD2;
}

3.3. Recover the sence

The DPF2 bit in PMU_CS1 register defines the Deep-sleep 2 mode status. If the DPF2 bit has been set, it indicates that the MCU has been entered Deep-sleep 2 mode. This bit is cleared by software by writing 0. When waked up from the Deep-sleep 2 mode, after system reset and apply the STACK 2, DPF2 will be checked, if DPF2 is 1, the SP and LR will be loaded with the values stored at address 0x20000000 and 0x20000004 respectively. Then the program jumps to the next line of the function pmu_deepsleep2_status_store and goes on.

Table 3-5. Recover the SP and LR

| If((PMU_CS1 & PMU_CS1_DPF2) == 2){ |
| PMU_CS1 = 0; |
| __asm__ __volatile__ |
| { |
|    "ldr r0,=0x20000000\n" |
|    /* load the value of 0x20000000 to SP */ |
| } |
Wakeup from Deep-sleep 2 and recover the scene

```
"ldr sp,[r0]\n"
"ldr r0,=0x20000004\n"
"ldr lr,[r0]\n"
"ldr lr,[r0]\n"
"pop {r0-r12}\n"
"bx lr\n"
```

When the program runs out of the function `pmu_to_deepsleepmode_2`, the configuration of the registers can be recovered by loading the values stored before entering the Deep-sleep 2 mode in the global variables.

**Table 3-6. Recover the sense**

```c
pmu_to_deepsleepmode_2(PMU_LDO_NORMAL, WFI_CMD);
/* recover the register configuration of EXMC */
EXMC_SNCTL0 = exmc_config[0];
EXMC_SNTCFG0 = exmc_config[1];
EXMC_SNWTCFG0 = exmc_config[2];
/* recover the register configuration of USART */
USART_BAUD(EVAL_COM0) = usart_config[0];
USART_CTL0(EVAL_COM0) = usart_config[1];
```

So far, a mechanism designed to recover the application scene has achieved the similar feature of Deep-sleep mode that the program could continue to run where it had entered low power mode.

Further more, if the application is much complex and the global variables exceed the first 32KB of SRAM, the real-time or important data can be scatter loading in the first 32KB of SRAM. And discard unimportant global variables when entering the Deep-sleep 2 mode.
4. Revision history

Table 4-1. Revision history

<table>
<thead>
<tr>
<th>Revision No.</th>
<th>Description</th>
<th>Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>1.0</td>
<td>Initial Release</td>
<td>Feb.24, 2021</td>
</tr>
</tbody>
</table>
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